MSE Package
16-Lead Plastic MSOP, Exposed Die Pad
(Reference LTC DWG # 05-08-1667 Rev F)

NOTE:
1. DIMENSIONS IN MILLIMETER/(INCH)
2. DRAWING NOT TO SCALE
3. DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.152mm (.006") PER SIDE
4. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS.
INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.152mm (.006") PER SIDE
5. LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.102mm (.004") MAX
6. EXPOSED PAD DIMENSION DOES INCLUDE MOLD FLASH. MOLD FLASH ON E-PAD SHALL NOT EXCEED 0.254mm (.010") PER SIDE.

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**Gauge Plane**

- **MIN**: 0.18 (.007)
- **MAX**: 0.53 ±0.152 (.021 ±0.006)

**Recommended Solder Pad Layout**

- **Width**: 0.254 (.010)
- **Length**: 0.50 (0197) BSC

**Seating Plane**

- **Center-to-Center**: 2.845 ±0.102 (.112 ±0.004)
- **Max**: 3.20 – 3.45 (.126 – .136)

**Bottom View of Exposed Pad Option**

- **Height**: 5.10 (.201) MIN
- **Width**: 0.889 ±0.127 (.035 ±0.005)

**Detail “A”**

- **Length**: 0.50 (.0197) BSC
- **Width**: 0.254 (.010)

**Detail “B”**

- **Height**: 4.039 ±0.102 (.159 ±0.004)
- **Max**: 4.90 ±0.152 (.193 ±0.006)

**Bottom View of Exposed Pad Option**

- **Center-to-Center**: 2.845 ±0.102 (.112 ±0.004)
- **Max**: 3.00 ±0.102 (.118 ±0.004)

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**NOTE:**
- **NOTE 3**: CORNER TAIL IS PART OF THE LEADFRAME FEATURE. FOR REFERENCE ONLY NO MEASUREMENT PURPOSE
- **NOTE 4**: FOR REFERENCE ONLY NO MEASUREMENT PURPOSE